**N&P-Channel MOSFET** 

# **General Description**

The WSF6012 is the highest performance trench N-ch and P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF6012 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

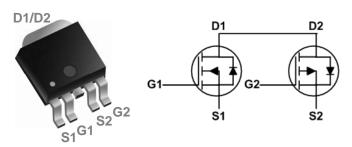
## **Product Summery**

BVDSS	RDSON	ID
60V	28mΩ	20A
-60V	46mΩ	-15A

# **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter.
- Networking DC-DC Power System
- Load Switch

## **TO-252-4L Pin Configuration**



# **Absolute Maximum Ratings**

		Rat	ing	
Symbol	Parameter	N-Channel	P-Channel	Units
$V_{DS}$	Drain-Source Voltage	60	-60	V
$V_{GS}$	Gate-Source Voltage	±20	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	-15	Α
I <sub>D</sub> @T <sub>C</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	15	-10	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	46	-36	Α
EAS	Single Pulse Avalanche Energy <sup>3</sup>	200	180	mJ
I <sub>AS</sub>	Avalanche Current	59	-50	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	34.7	34.7	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	-55 to 150	$^{\circ}$
$T_J$	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^{\circ}$

# **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		85	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		50	°C/W



# N-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.063		V/°C
В	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =8A		28	37	<b>~~</b> 0
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =5A		37	45	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	\/ -\/   -250A	1		2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-5.24		mV/℃
1	Drain Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	<sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃		1	uA
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	T UA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =8A		21		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		3.0	4.5	Ω
$Q_g$	Total Gate Charge (4.5V)			12.6	20	
$Q_{gs}$	Gate-Source Charge	$V_{DS}$ =48V , $V_{GS}$ =4.5V , $I_{D}$ =8A		3.5		nC
$Q_{gd}$	Gate-Drain Charge			6.3		
T <sub>d(on)</sub>	Turn-On Delay Time			8		
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =4.5V ,		14.2		20
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=3.3\Omega$ , $I_D=1A$		24.6		ns
T <sub>f</sub>	Fall Time			4.6		
C <sub>iss</sub>	Input Capacitance			670		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		70		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			35		

## **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.1mH , I <sub>AS</sub> =16A	100			mJ

# **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	-V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				60	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1.7A,T <sub>J</sub> =25℃			1.4	V

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10 sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =16A
- 4.The power dissipation is limited by 150 °C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



**N&P-Channel MOSFET** 

# P-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-60			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^{\circ}$ C , I <sub>D</sub> =-1mA		-0.03		V/℃
Passau	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-5A		46	60	mΩ
R <sub>DS(ON)</sub>		$V_{GS}$ =-4.5 $V$ , $I_D$ =-3 $A$		65	90	11122
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . I <sub>D</sub> =-250uA	-1.0		-2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> -V <sub>DS</sub> , I <sub>D</sub> 2300A		4.56		mV/℃
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =-48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	uA
DSS	Diani-Source Leakage Current	$V_{DS}$ =-48 $V$ , $V_{GS}$ =0 $V$ , $T_J$ =55 $^{\circ}$ C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}$ =0V			±100	nA
gfs	Forward Transconductance	$V_{DS}$ =-5V , $I_D$ =-4.5A		15		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.5	2.7	Ω
Qg	Total Gate Charge (-4.5V)			10		
$Q_gs$	Gate-Source Charge	$V_{DS}$ =-48V , $V_{GS}$ =-4.5V , $I_{D}$ =-5A		3.1		nC
$Q_gd$	Gate-Drain Charge			3.0		
T <sub>d(on)</sub>	Turn-On Delay Time			9.7		
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =-20V , V <sub>GS</sub> =-10V ,		19		20
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=3.3\Omega, I_D=-1A,$		46		ns
T <sub>f</sub>	Fall Time			45.8		
C <sub>iss</sub>	Input Capacitance			500		
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		66		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			32		

## **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =-25V , L=0.1mH , I <sub>AS</sub> =-10A	90			mJ

# **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,6</sup>	-V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			-15	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				-50	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25℃			-1.2	V

#### Note

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =-25V,  $V_{GS}$ =-10V, L=0.1mH,  $I_{AS}$ =-10A
- 4.The power dissipation is limited by 150℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **N-Channel Typical Characteristics**

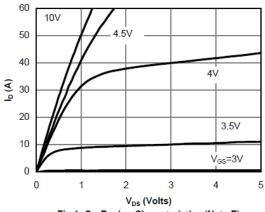


Fig 1: On-Region Characteristics (Note E)

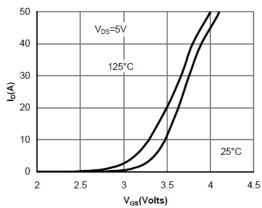


Figure 2: Transfer Characteristics (Note E)

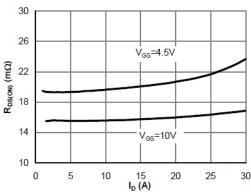


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

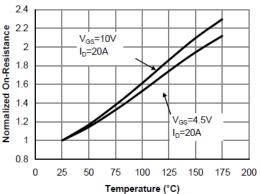


Figure 4: On-Resistance vs. Junction Temperature (Note E)

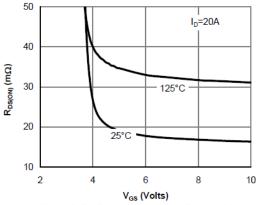


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

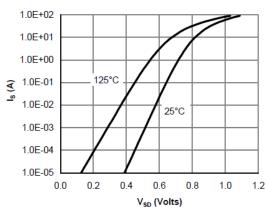
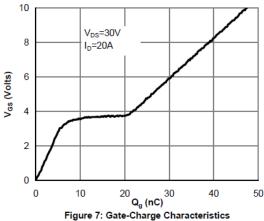
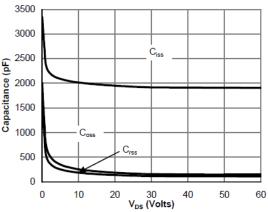


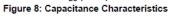
Figure 6: Body-Diode Characteristics (Note E)











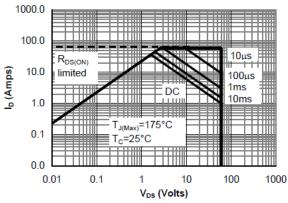


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

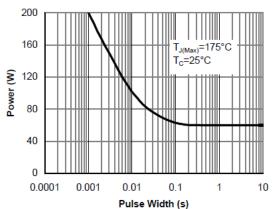


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

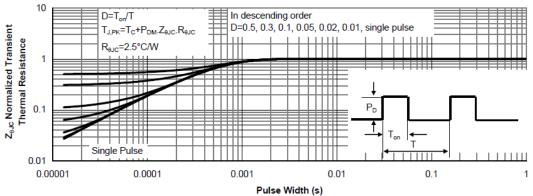
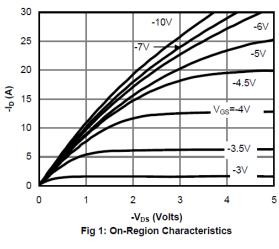
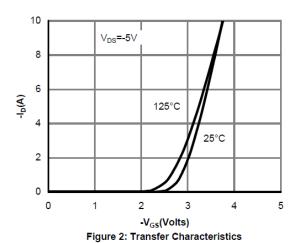


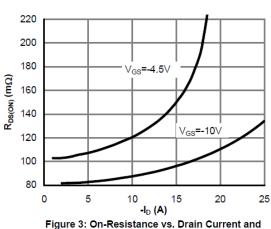
Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

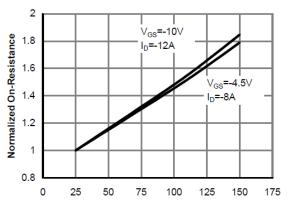


# **P-Channel Typical Characteristics**

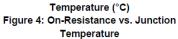


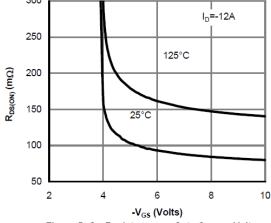












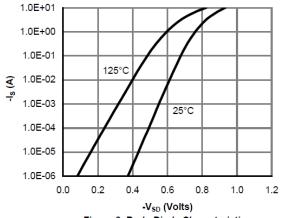
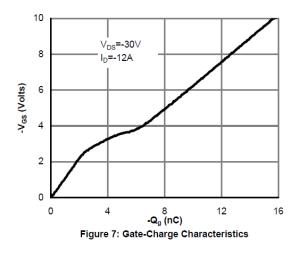
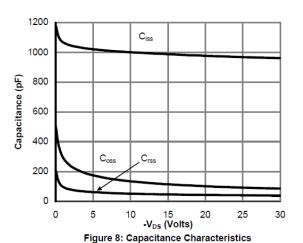


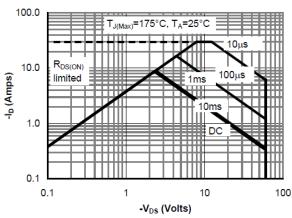
Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics









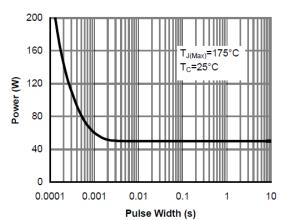


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

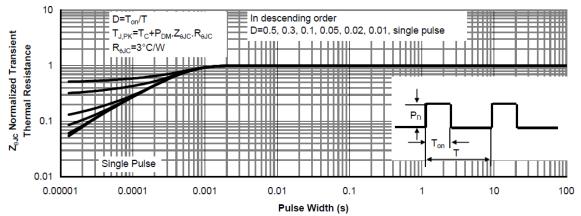


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)



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